PATENT ASSIGNMENT

Electronic Version v1.1
Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Memscap S.A.	03/20/2008

RECEIVING PARTY DATA

Name:	Sakura Technologies, LLC
Street Address:	2711 Centerville Road, Suite 400
City:	Wilmington
State/Country:	DELAWARE
Postal Code:	19808

PROPERTY NUMBERS Total: 9

Property Type	Number
Patent Number:	6542060
Patent Number:	6529110
Patent Number:	6456183
Patent Number:	6838970
Patent Number:	6727138
Patent Number:	6459135
Patent Number:	6548365
Patent Number:	6429764
Patent Number:	6713199

OP $360.00 6542060

CORRESPONDENCE DATA

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Total Attachments: 6
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Exhibit B1

ASSIGNMENT OF PATENT RIGHTS

For good and valuable consideration, the receipt of which is hereby acknowledged, MEMSCAP S.A., a French corporation having offices at Parc Activillage des Fontaines, Bernin, 38926 Crolles Cedex, France, (***"Assignor"***), subject to the Prior Granted Licenses (as in Exhibit. C1 to the Patent Purchase Agreement between Assignor and Assignee dated September 28, 2007 (the "PPA")) and to the Seller License (as defined in the PPA), does hereby sell, assign, transfer, and convey unto Sakura Technologies, LLC, a State of Delaware limited liability company, having an office at 2711 Centerville Road, Suite 400, Wilmington, Delaware, 19808, U.S.A. (***"Assignee"***), all right, title, and interest that exist today and may exist in the future in and to all of the following **listed in Attachment** (collectively, the ***"Patent Rights"***), including:

(a) the provisional patent applications, patent applications and patents listed in Attachment hereto ("Listed Patents"),

(b) all patents or patent applications filed by Assignee (or any subsequent transferee of any Patent Rights) after the date of this Assignment of Patent Rights (i) to which any of the foregoing forms a basis for priority, (ii) that are reissues, reexaminations, extensions, continuations, continuations in part, continuing prosecution applications, or divisions of any of the foregoing, and/or (iii) that are foreign counterparts to any of the foregoing, including certificates of invention, utility models, industrial design protection, design patent protection, and other governmental grants;

(c) all patents, patent applications and/or other governmental grants or issuances of any type that (i) are filed by Assignee (or any transferee of any Patent Rights) after the date of this Assignment of Patent Rights and claim priority, directly or indirectly, to any Listed Patent and (ii) are related to any of the inventions, invention disclosures, and discoveries described in any of the Listed Patents to the extent that any such inventions, invention disclosures, and discoveries (x) are included in any claim in the Listed Patents, (y) are subject matter capable of being reduced to a patent claim in any reissue or reexamination proceedings brought on any of the Listed Patents and/or (z) could have been and/or could be included as a claim in any continuations, continuations in part, continuing prosecution applications, requests for continuing examinations and/or divisions of the Listed Patents;

(d) rights to apply in any or all countries of the world for patents, certificates of invention, utility models, industrial design protections, design patent protections or other governmental grants of any type related to the any of the foregoing categories (a), (b), and/or (c), including, without limitation, under the Paris Convention for the Protection of Industrial Property, the International Patent Cooperation Treaty, or any other convention, treaty, agreement or understanding;

(e) causes of action (whether currently pending, filed, or otherwise) and other enforcement rights, including, without limitation, all rights under the provisional patent applications, patent applications and patents listed below and/or under or on account of any of the foregoing categories (b), (c) and/or (d) to

(i) damages,
(ii) injunctive relief and
(iii) other remedies of any kind

for past, current and future infringement; and

(f) all rights to collect royalties and other payments under or on account of any of the Listed Patents,

or any of the foregoing categories (b) through (e).

Assignor represents warrants and covenants that:

(1)Assignor has the full power and authority, to enter into this Agreement and to carry out its obligations hereunder, including the assignment of the Patent Rights to Assignee;

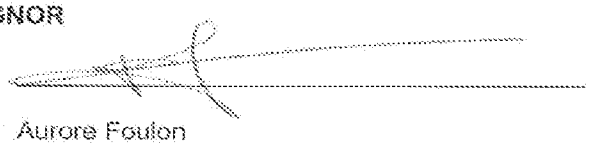
(2)Assignor owns all right, title, and interest to the Patent Rights, including, without limitation, all right, title, and interest to sue for infringement of the Patent Rights. . The Patent Rights are free and clear of all liens, claims, mortgages, security interests or other encumbrances, and restrictions. There are no actions, suits, investigations, claims or proceedings threatened, pending or in progress relating in any way to the Patent Rights. There are no existing contracts, agreements, options, commitments, proposals, bids, offers, or rights with, to, or in any person to acquire any of the Patent Rights.

Assignor hereby authorizes the respective patent office or governmental agency in each jurisdiction to issue any and all patents, certificates of invention, utility models or other governmental grants or issuances that may be granted upon any of the Patent Rights in the name of Assignee, as the assignee to the entire interest therein.

The terms and conditions of this Assignment of Patent Rights will inure to the benefit of Assignee, its successors, assigns, and other legal representatives and will be binding upon Assignor, its successors, assigns, and other legal representatives.

IN WITNESS WHEREOF this Assignment of Patent Rights is executed at Bernin, France on this 20th day of March 2008.

ASSIGNOR

By: 

Name: Aurore Foulon

Title: Genera Counsel

Attachment
Listed Patents

Appln. No.	Patent No.	Title	Country	Filing Date
FR0011577		Microcomponent Of The Type Microinductance Or Microtransformer	FR	9/12/2000
09/943,604	6,542,060	Microcomponent Of The Microinductor Or Microtransformer Type	US	8/30/2001
EP01420186.7		Microcomponent Of The Type Microinductance Or Microtransformer	EP	9/5/2001
CA2357196		Microcomponent Of Micro-Inductance Or Microprocessor Type	CA	9/11/2001
JP2001-276880		Fine Element Of Type Such As Minute Inductor And Minute Transformer	JP	9/12/2001
FR0008413		Microcomponent Of Microinductance Or Microtransformer Type	FR	6/29/2000
09/870,819	6,529,110	Microcomponent Of The Microinductor Or Microtransformer Type	US	5/31/2001
EP01420135.4		Microcomponent Of Microinductance Or Microtransformer Type	EP	6/13/2001
CA2351790		Microinductance Or Microtransformer Type Microcomponent	CA	6/28/2001
JP2001-197086		Microinductor Or Microelement Or Microtransformer Type	JP	6/28/2001
FR9902658		Inductive Component, Integrated Transformer, In Particular For A Radio Frequency Circuit, And Associated Integrated Circuit With Such Inductive Component Or Integrated Transformer	FR	2/26/1999
CA2298318		Inductive Component, Integrated Transformer, Intended To Be Incorporated Into A Radio Frequency Circuit, And Integrated Circuit Associated With The Said Inductive Component Or Integrated Transformer	CA	2/10/2000
EP00420039.0		Inductive Component, Integrated Transformer, In Particular For A Radio Frequency Circuit, And Associated Integrated Circuit With Such Inductive Component Or Integrated Transformer	EP	2/22/2000
JP2000-047980		Inductor Element And Integrated Transformer Intended Particularly To Be Incorporated In High-Frequency Circuit, And Integrated Circuit Incorporating Such Inductor Element Or Integrated Circuit	JP	2/24/2000
09/511,748	6,456,183	Inductor For Integrated Circuit	US	2/24/2000
10/206,284	6,838,970	Inductor For Integrated Circuit	US	7/26/2002
FR0115456		Manufacture Of Electronic Component Incorporating Inductive Microcomponent, Comprises Etching Copper-Diffusion Barrier Layer Between Turns Of Inductive Microcomponent	FR	11/29/2001

Appln. No.	Patent No.	Title	Country	Filing Date
CA2409237		Process For The Manufacture Of An Electronic Component Containing An Inductive Micro-Component	CA	10/21/2002
EP02356230.9		Method Of Manufacturing An Electronic Device Comprising An Inductive Micro Component	EP	11/18/2002
10/303,401	6,727,138	Process For Fabricating An Electronic Component Incorporating An Inductive Microcomponent	US	11/25/2002
JP2002-346551		Method Of Manufacturing Electronic Component Incorporated With Guidance Micro Component	JP	11/28/2002
FR0115458		Fabrication of electronic component incorporating inductive microcomponent, e.g. inductor or transformer, comprises etching copper-diffusion barrier layer between turns of inductive microcomponent	FR	11/29/2001
CA2409232		PROCESS FOR THE MANUFACTURE OF AN ELECTRONIC COMPONENT CONTAINING AN INDUCTIVE MICRO-COMPONENT	CA	10/21/2002
EP02356231.7		Fabrication process for electronic component with incorporated microinductance	EP	11/18/2002
10/303,466		Process For Fabricating An Electronic Component Incorporating An Inductive Microcomponent	US	11/25/2002
JP2002-346552		METHOD OF MANUFACTURING ELECTRONIC COMPONENT INCORPORATED WITH GUIDANCE MICRO COMPONENT	JP	11/28/2002
FR0115960		Manufacturing process of an electronic device comprising an inductive micro component	FR	12/11/2001
TW20020103959		Process for fabricating an electronic component incorporating an inductive microcomponent	TW	3/4/2002
CA2409241		PROCESS FOR MANUFACTURING AN ELECTRONIC COMPONENT INCORPORATING AN INDUCTIVE MICROCOMPONENT	CA	10/21/2002
EP20020356232		Manufacturing process of an electronic device comprising an inductive micro component	EP	11/18/2002
10/303,627		Process For Fabricating An Electronic Component Incorporating An Inductive Microcomponent	US	11/25/2002
JP2002-351667		METHOD OF MANUFACTURING ELECTRONIC COMPONENT INCORPORATED WITH GUIDANCE MICRO COMPONENT	JP	12/3/2002
FR9903762		Monolithic Integrated Circuit Comprising An Inductor And A Method Of Fabricating The Same	FR	3/23/1999
09/525,840	6,459,135	Monolithic Integrated Circuit Incorporating An Inductive Component And Process For Fabricating Such An Integrated Circuit	US	3/15/2000
EP00420046.5		Monolithic Integrated Circuit Comprising An Inductor And A Method Of Fabricating The Same	EP	3/21/2000
CA2301988		Monolithic Integrated Circuit With A Built-In Inductive Component And Procedure For Fabricating Such An Integrated Circuit	CA	3/22/2000
JP2000-080808		Integrated Circuit With Incorporated Inductive Element And Manufacture Of The Same	JP	3/22/2000

Appln. No.	Patent No.	Title	Country	Filing Date
10/177,435	6,548,365	Monolithic Integrated Circuit Incorporating An Inductive Component And Process For Fabricating Such An Integrated Circuit	US	6/21/2002
FR9906433		Microcomponents Of Microinductance Or Microtransformer Type And Manufacturing Process	FR	5/18/1999
09/558,641	6,429,764	Microcomponents Of The Microinductor Or Microtransformer Type And Process For Fabricating Such Microcomponents	US	4/26/2000
JP2000-133972		Microelement, Such As Microinductor, Micro-Transformer, Or The Like, And Manufacture Of Such Microelements	JP	5/2/2000
EP00420093.7		Microcomponents Of Microinductance Or Microtransformer Type And Manufacturing Process	EP	5/10/2000
CA2308871		Micro-Inductance Or Micro-Transformer Micro-Components, And Manufacturing Process For Such Micro-Components	CA	5/11/2000
FR0117069		Electronic Component Incorporating An Integrated Circuit And A Planar Microcondenser	FR	12/31/2001
FR0201618		Electronic Micro Component Including A Capacitive Structure	FR	2/11/2002
FR0202461		Multiplayer Structure Composed Of Alloy Layers Formed From Hafnium Dioxide, Zirconium Dioxide And Alumina For Microelectronic Applications	FR	2/27/2002
TW91103955	180449	Electronic Component Incorporating An Integrated Circuit And A Planar Microcapacitor	TW	3/4/2002
FR0203442		Multiplayer Structure Composed Of Alloy Layers Formed From Hafnium Dioxide, Zirconium Dioxide And Alumina For Microelectronic Applications	FR	3/20/2002
FR0203444		Multiplayer Structure Composed Of Alloy Layers Formed From Hafnium Dioxide, Zirconium Dioxide And Alumina For Microelectronic Applications	FR	3/20/2002
FR0203445		Multiplayer Structure Composed Of Alloy Layers Formed From Hafnium Dioxide, Zirconium Dioxide And Alumina For Microelectronic Applications	FR	3/20/2002
FR0204782		Multiplayer Structure Composed Of Alloy Layers Formed From Hafnium Dioxide, Zirconium Dioxide And Alumina For Microelectronic Applications	FR	4/17/2002
FR0209458		No English title available	FR	7/25/2002
FR0209459		No English title available	FR	7/25/2002
EP02356255.6		Electronic Component Comprising An Integrated Circuit And A Planar Micro Capacitor	EP	12/10/2002
CA2414400		Electronic Component Incorporating An Integrated Circuit And A Planar Microcondenser	CA	12/10/2002
10/318,892		Electronic Component Incorporating An Integrated Circuit And A Planar Microcondenser	US	12/13/2002
CA2415324		Multiplayer Structure, Used In Particular As A Material With High Relative Permittivity	CA	12/23/2002
10/328,880		Multi-Layer Structure Used Especially As A Material Of High Relative Permittivity	US	12/24/2002

Appln. No.	Patent No.	Title	Country	Filing Date
10/328,881		Multiplayer Structure Used Especially As A Material Of High Relative Permittivity	US	12/24/2002
10/329,115	6,713,199	Multiplayer Structure Used Especially As A Material Of High Relative Permittivity	US	12/24/2002
JP2002-378528		Multi-Layer Structure Used Particularly As Substance With High Relative Permittivity	JP	12/26/2002
JP2002-378529		Multilayer Structure Used Especially As Material Of High Relative Permittivity	JP	12/26/2002
JP2002-378530		Multilayer Structure Used In Particular As Material With High Relative Permittivity	JP	12/26/2002
JP2002-378532		Integrated Circuit, And Electronic Component Having Planar Micro-Capacitor Integrated Thereinto	JP	12/26/2002
EP02102893.1		Multilayer Structure	EP	12/26/2002
EP02102892.3		No English title available	EP	12/26/2002
EP02102894.9		Multilayer Structure And Material With High Permittivity	EP	12/26/2002
CA2415309		Multiplayer Structure, Used In Particular As A Material With High Relative Permittivity	CA	12/30/2002
CA2415312		Multiplayer Structure, Used In Particular As A Material With High Relative Permittivity	CA	12/30/2002
PCT/FR2003/00231		Electronic Micro Component Including A Capacitive Structure	WO	1/24/2003
EP03100394.0		Electronic Microcomponent Comprising A Capacity Structure And Its Method Of Fabrication	EP	2/20/2003
10/374,354		Electronic Microcomponent Including A Capacities Structure, And Process For Producing It	US	2/25/2003
CA2420308		Electronic Microcomponent Incorporating A Capacitive Structure And Development Process	CA	2/25/2003
JP2003-051816		Electronic Microcomponent Including Capacitive Structure And Its Manufacturing Method	JP	2/27/2003
10/379,754		Electronic Microcomponent Inculpating A Capacitive Structure And Fabrication Process	US	3/5/2003
EP03100542.4		Electronic Microcomponent Integrating A Capacity Structure And Corresponding Fabrication Method	EP	3/5/2003
CA2421110		Electronic Micro-Component Incorporating A Capacitive Structure And Manufacturing Process	CA	3/12/2003
JP2003-076543		Electronic Microcomponent Provided With Capacitance Structure And Its Manufacturing Method	JP	3/19/2003
PCT/FR2003/01245		Method For Production Of A Capacitive Structure Above A Metallization Level Of An Electronic Component	WO	4/17/2003
10/425,415		Multiplayer Structure Used Especially As A Material Of High Relative Permittivity	US	4/29/2003
FR0205465	2834242	No English title available	FR	4/30/2002